

U.S. Patent Application S.N. 09/525,247

YAMAP0347USB

DRAFT AMENDED CLAIMS

8. (Amended) A lamination ceramic chip inductor, comprising at least one fine, continuous conductive pattern, the at least one conductive pattern having a thickness of 10 μm or more and a width to thickness ratio from 1 to less than 5.

12. (Amended) A lamination ceramic chip inductor, comprising at least one fine, continuous conductive pattern formed by an electroforming process using a photoresist, the at least one conductive pattern having a thickness of 10 μm or more and a width to thickness ratio from 1 to less than 5.

21. (Amended) A lamination ceramic chip inductor, comprising at least one fine, continuous conductive pattern formed between at least one pair of insulation layers so as to have no specific gap between the at least one conductive pattern and the at least one pair of insulation layers, the at least one conductive pattern having a thickness of 10 μm or more and a width to thickness ratio from 1 to less than 5.

25. (Amended) A lamination ceramic chip inductor, comprising at least one fine, continuous conductive pattern formed by an electroforming process using a photoresist, the at least one conductive pattern having a thickness of 10 μm or more and a width to thickness ratio from 1 to less than 5,

wherein the at least one conductive pattern is formed between at least one pair of insulation layers so as to have no specific gap therebetween.

29. (Amended) A lamination ceramic chip inductor, comprising at least one conductive pattern formed between at least one pair of insulation layers so as to have no specific gap between the at least one conductive pattern and the at least one pair of insulation layers, the at least one conductive pattern consisting of metal selected from the group consisting of Ag, Au, Pt, Pd, Cu, Ni and alloys thereof.

34. (Amended) A lamination ceramic chip inductor, comprising at least one conductive pattern formed by an electroforming process using a photoresist,

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wherein the at least one conductive pattern is formed between at least one pair of insulation layers so as to have no specific gap therebetween, and the at least one conductive pattern consisting of metal selected from the group consisting of Ag, Au, Pt, Pd, Cu, Ni and alloys thereof.